



AF/IFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applicant:

Brian Taggart et al.

Serial No.: 10/807,830

Filed: March 24, 2004

For: Lower Profile Flexible Substrate
Package for Electronic Components

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Art Unit: 2818

Examiner: Calvin Lee

Docket: ITL.1119US
P18791

Assignee: Intel Corporation

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REPLY TO FINAL REJECTION

Sir:

In response to the final rejection mailed June 24, 2005, please amend the above-referenced patent application as follows:

Date of Deposit: July 6, 2005

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class mail** with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Cynthia L. Hayden
Cynthia L. Hayden